

# MOSFET – Power, N-Channel, SUPERFET® III, FRFET®

**650 V, 75 A, 27.4 mΩ**

## NVHL027N65S3F

### Description

SUPERFET III MOSFET is onsemi's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET is very suitable for the various power system for miniaturization and higher efficiency.

SUPERFET III FRFET MOSFET's optimized reverse recovery performance of body diode can remove additional component and improve system reliability.

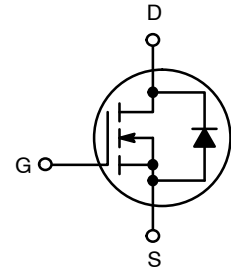
### Features

- 700 V @  $T_J = 150\text{ }^\circ\text{C}$
- Typ.  $R_{DS(on)} = 21.5\text{ m}\Omega$
- Ultra Low Gate Charge (Typ.  $Q_g = 227\text{ nC}$ )
- Low Effective Output Capacitance (Typ.  $C_{oss(eff.)} = 1880\text{ pF}$ )
- 100% Avalanche Tested
- AEC-Q101 Qualified and PPAP Capable

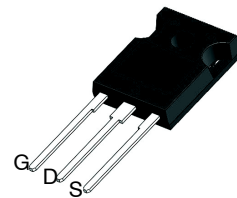
### Applications

- Automotive On Board Charger HEV-EV
- Automotive DC/DC Converter for HEV-EV

$V_{DSS}$	$R_{DS(on)}\text{ MAX}$	$I_D\text{ MAX}$
650 V	27.4 mΩ @ 10 V	75 A

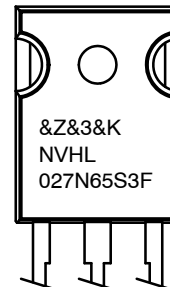


**POWER MOSFET**



**TO-247 LONG LEADS  
CASE 340CX**

### MARKING DIAGRAM



- &Z = Assembly Plant Code
- &3 = Data Code (Year & Week)
- &K = Lot
- NVHL027N65S3F = Specific Device Code

### ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

# NVHL027N65S3F

## ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25 °C, Unless otherwise noted)

Symbol	Parameter	NVHL027N65S3F	Unit
V <sub>DSS</sub>	Drain to Source Voltage	650	V
V <sub>GSS</sub>	Gate to Source Voltage	- DC	±30
		- AC (f > 1 Hz)	±30
I <sub>D</sub>	Drain Current	- Continuous (T <sub>C</sub> = 25 °C)	75
		- Continuous (T <sub>C</sub> = 100 °C)	60
I <sub>DM</sub>	Drain Current	- Pulsed (Note 1)	187.5
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)	1610	mJ
I <sub>AS</sub>	Avalanche Current (Note 2)	15	A
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)	5.95	mJ
dv/dt	MOSFET dv/dt	100	V/ns
	Peak Diode Recovery dv/dt (Note 3)	50	
P <sub>D</sub>	Power Dissipation	(T <sub>C</sub> = 25 °C)	595
		- Derate Above 25 °C	4.76
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to +150	°C
T <sub>L</sub>	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. I<sub>AS</sub> = 15 A, R<sub>G</sub> = 25 Ω, starting T<sub>J</sub> = 25 °C.
3. I<sub>SD</sub> ≤ 37.5 A, di/dt ≤ 200 A/μs, V<sub>DD</sub> ≤ 400 V, starting T<sub>J</sub> = 25 °C.

## THERMAL CHARACTERISTICS

Symbol	Parameter	NVHL027N65S3F	Unit
R <sub>θJC</sub>	Thermal Resistance, Junction to Case, Max.	0.21	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient, Max.	40	

## PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NVHL027N65S3F	NVHL027N65S3F	TO-247	Tube	N/A	N/A	30 Units

# NVHL027N65S3F

## ELECTRICAL CHARACTERISTICS ( $T_C = 25\text{ }^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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### OFF CHARACTERISTICS

BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA, T <sub>J</sub> = 25 °C	650			V
		V <sub>GS</sub> = 0 V, I <sub>D</sub> = 10 mA, T <sub>J</sub> = 150 °C	700			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 20 mA, Referenced to 25 °C		0.61		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 650 V, V <sub>GS</sub> = 0 V			10	μA
		V <sub>DS</sub> = 520 V, T <sub>C</sub> = 125 °C		590		
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0 V			±100	nA

### ON CHARACTERISTICS

V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 3 mA	3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 35 A		21.5	27.4	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 37.5 A		57		S

### DYNAMIC CHARACTERISTICS

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 400 V, V <sub>GS</sub> = 0 V, f = 1 MHz		7780		pF
C <sub>oss</sub>	Output Capacitance			200		pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V		1880		pF
C <sub>oss(er.)</sub>	Energy Related Output Capacitance	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V		347		pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10 V	V <sub>DS</sub> = 400 V, I <sub>D</sub> = 37.5 A, V <sub>GS</sub> = 10 V (Note 4)		227		nC
Q <sub>gs</sub>	Gate to Source Gate Charge			67		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge			87		nC
ESR	Equivalent Series Resistance	f = 1 MHz		2.2		Ω

### SWITCHING CHARACTERISTICS

t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 400 V, I <sub>D</sub> = 37.5 A, V <sub>GS</sub> = 10 V R <sub>g</sub> = 2 Ω (Note 4)		46		ns
t <sub>r</sub>	Turn-On Rise Time			59		ns
t <sub>d(off)</sub>	Turn-Off Delay Time			147		ns
t <sub>f</sub>	Turn-Off Fall Time			42		ns

### SOURCE-DRAIN DIODE CHARACTERISTICS

I <sub>S</sub>	Maximum Continuous Source to Drain Diode Forward Current			75		A
I <sub>SM</sub>	Maximum Pulsed Source to Drain Diode Forward Current			187.5		A
V <sub>SD</sub>	Source to Drain Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 37.5 A		1.3		V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 37.5 A, dI <sub>F</sub> /dt = 100 A/μs		179		ns
Q <sub>rr</sub>	Reverse Recovery Charge			1098		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

TYPICAL PERFORMANCE CHARACTERISTICS

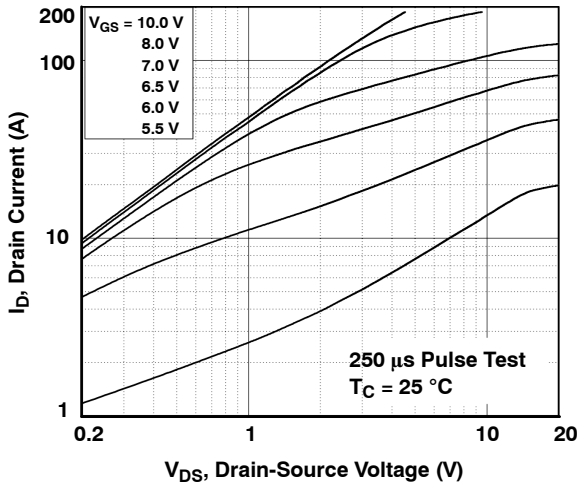


Figure 1. On-Region Characteristics

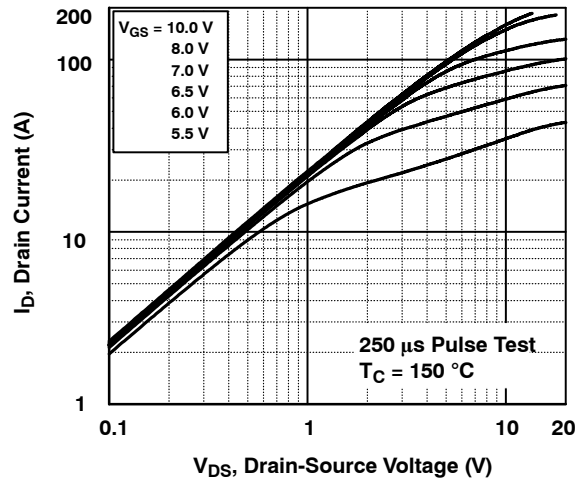


Figure 2. On-Region Characteristics

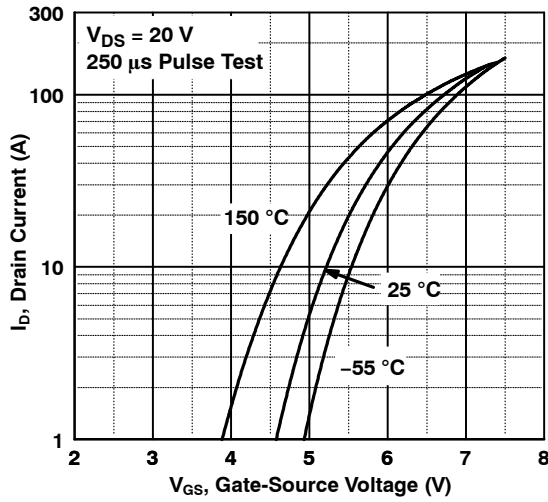


Figure 3. Transfer Characteristics

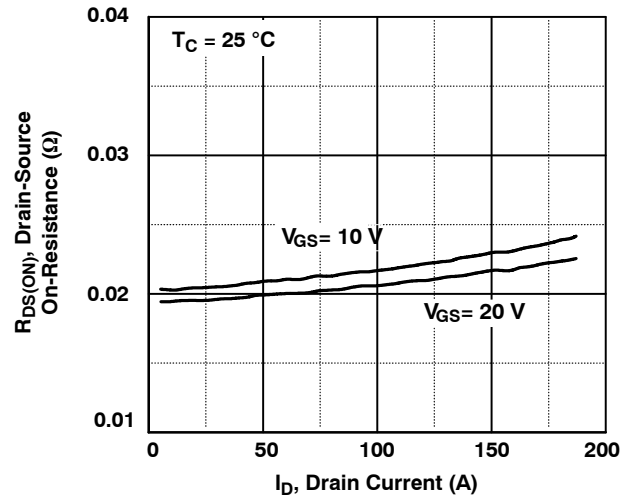


Figure 4. On-Resistance Variation vs. Drain Current and Gate Voltage

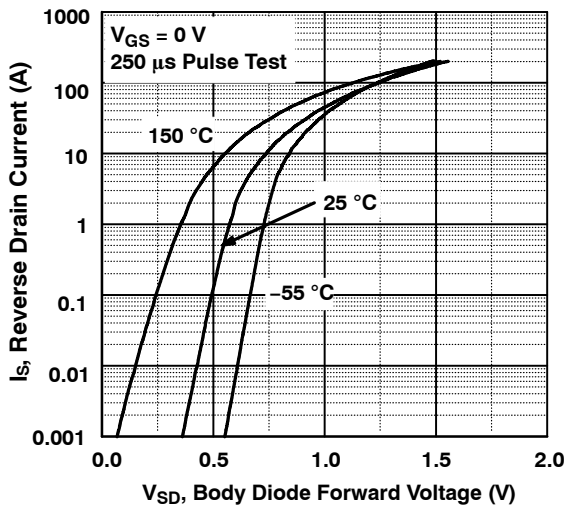


Figure 5. Body Diode Forward Voltage Variation vs. Source Current and Temperature

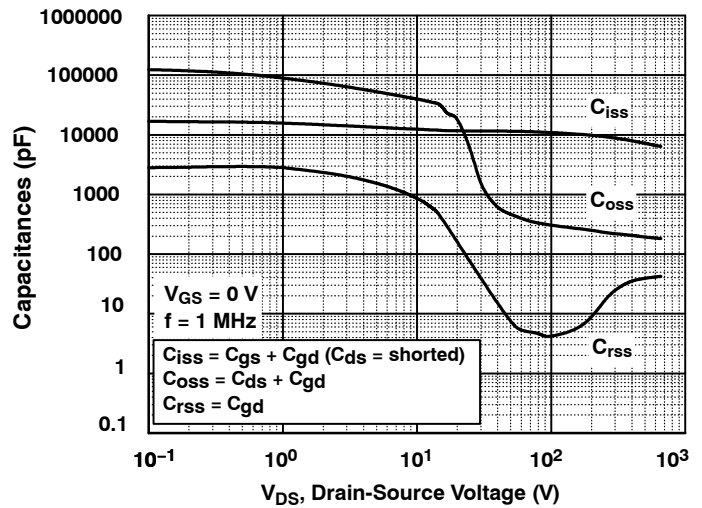


Figure 6. Capacitance Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

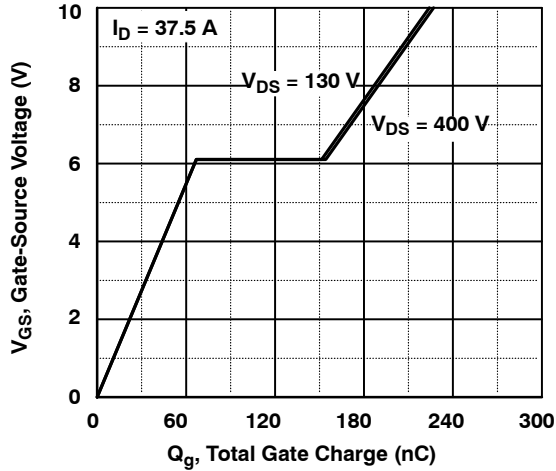


Figure 7. Gate Charge Characteristics

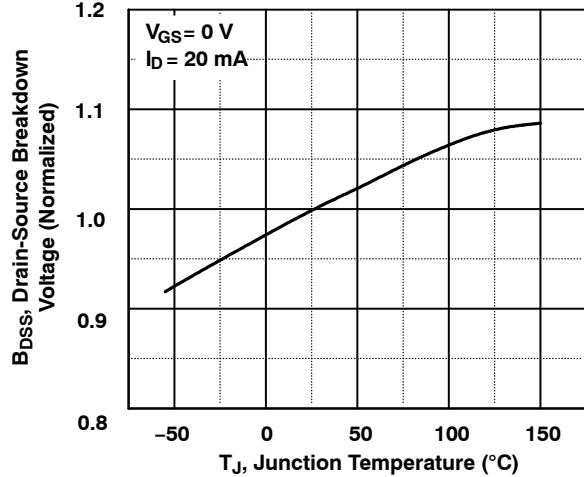


Figure 8. Breakdown Voltage Variation vs. Temperature

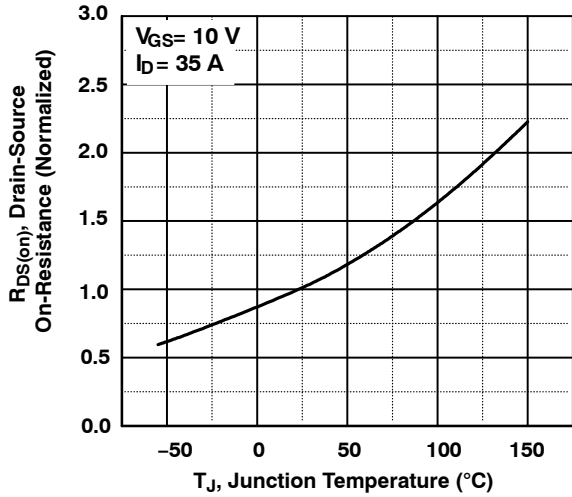


Figure 9. On-Resistance Variation vs. Temperature

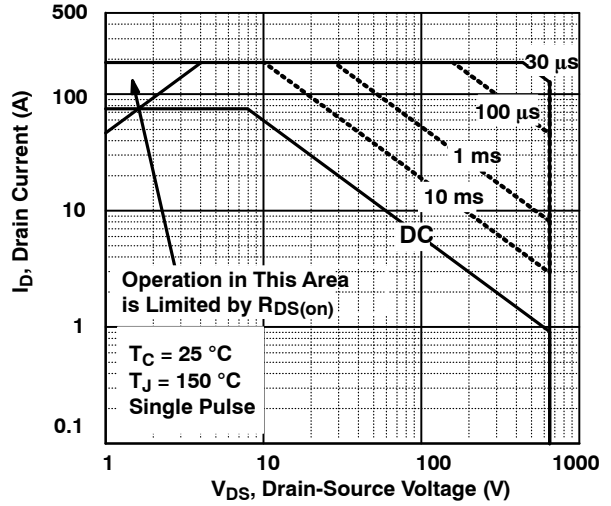


Figure 10. Maximum Safe Operating Area

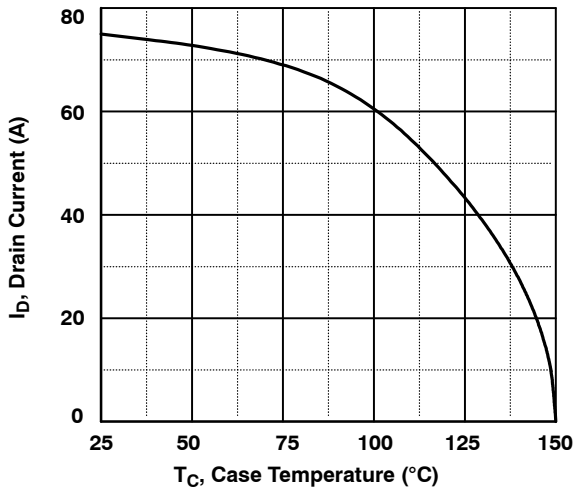


Figure 11. Maximum Drain Current vs. Case Temperature

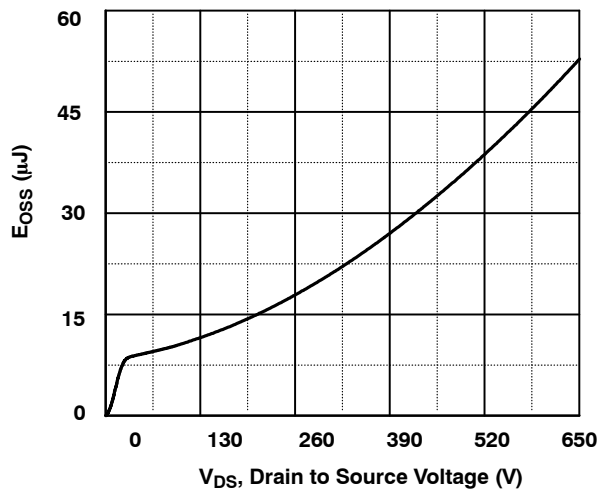


Figure 12.  $E_{OSS}$  vs. Drain to Source Voltage

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

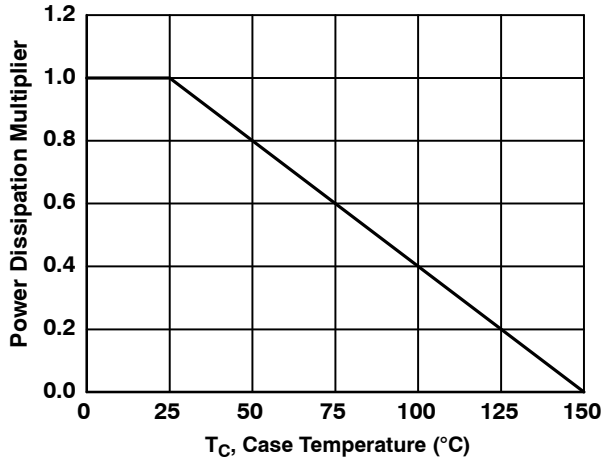


Figure 13. Normalized Power Dissipation vs. Case Temperature

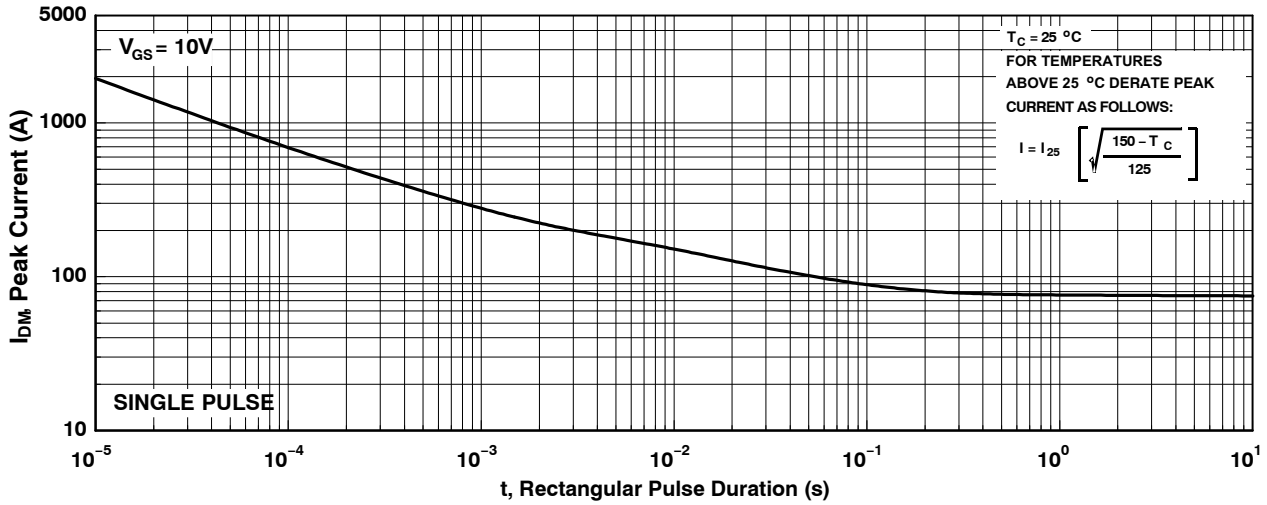
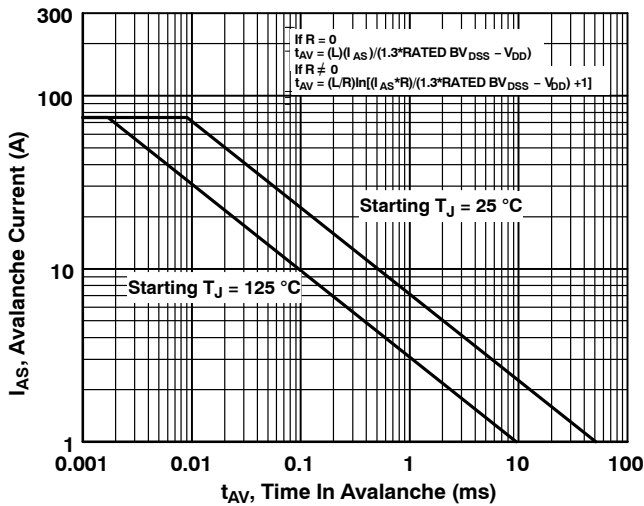


Figure 14. Peak Current Capability



NOTE: Refer to onsemi Application notes AN-7514/D and AN-7515/D

Figure 15. Unclamped Inductive Switching Capability

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

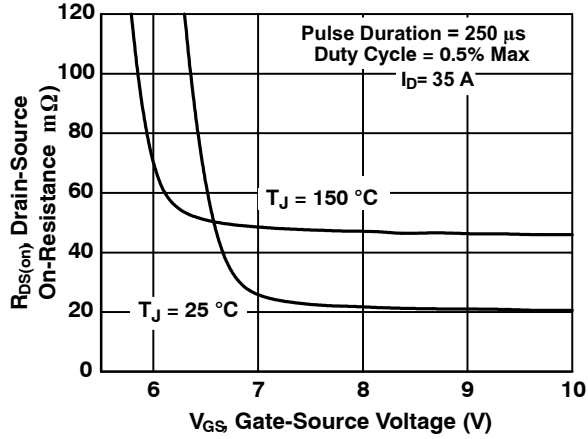


Figure 16. RDSON vs. Gate Voltage

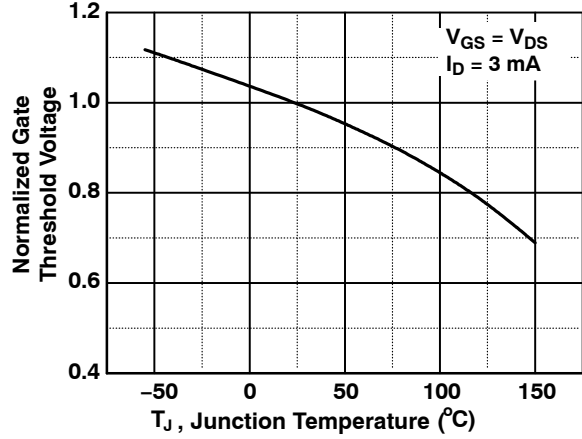


Figure 17. Normalized Gate Threshold Voltage vs. Temperature

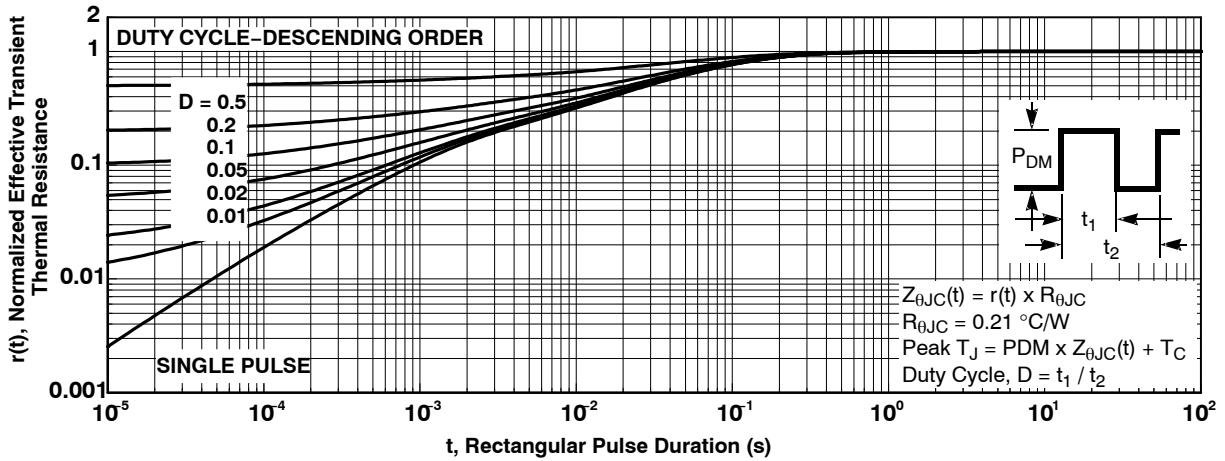


Figure 18. Transient Thermal Response Curve

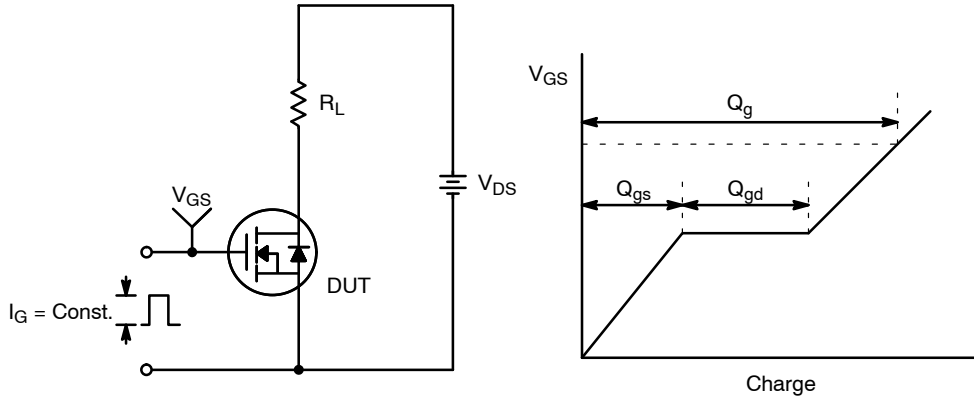


Figure 19. Gate Charge Test Circuit & Waveform

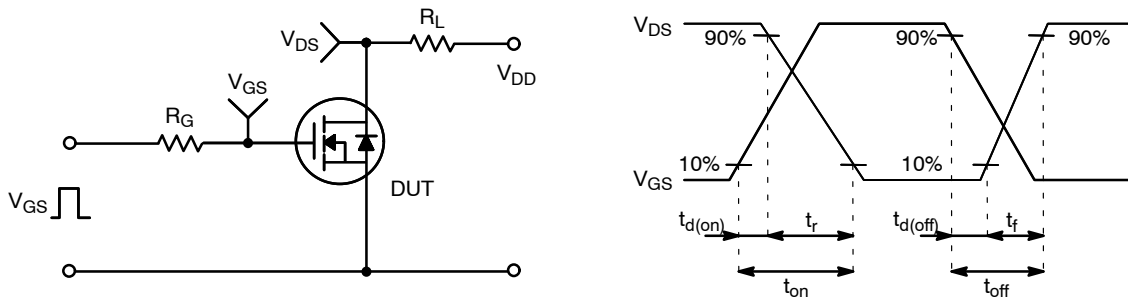


Figure 20. Resistive Switching Test Circuit & Waveforms

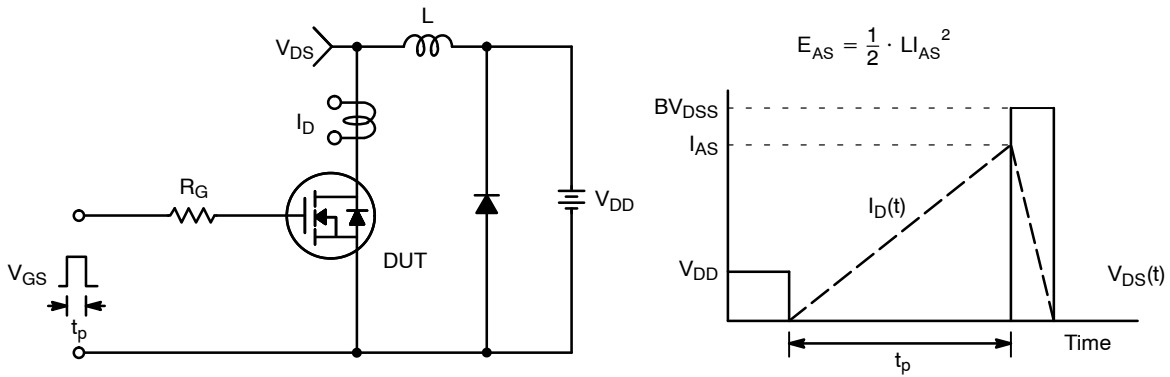
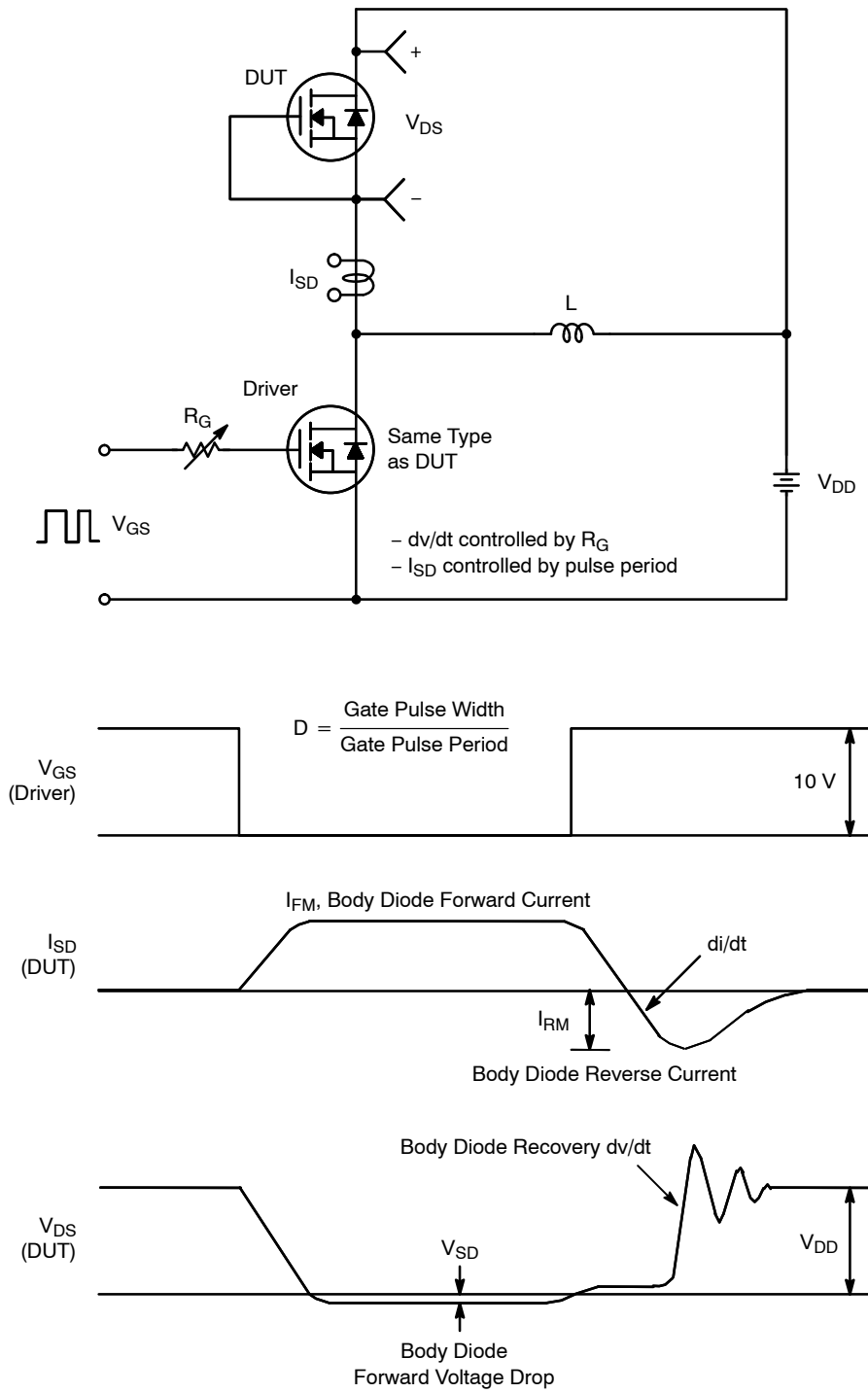


Figure 21. Unclamped Inductive Switching Test Circuit & Waveforms

# NVHL027N65S3F



**Figure 22. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms**

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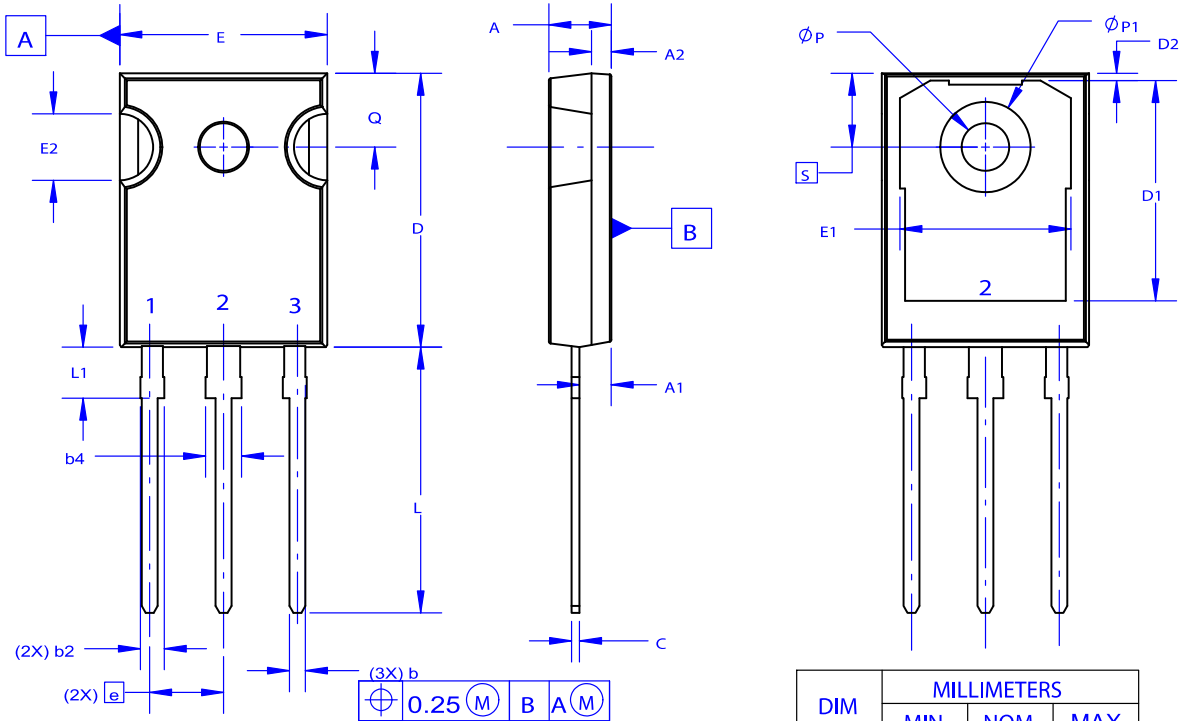
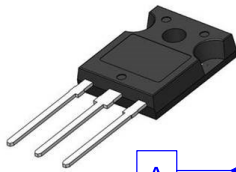
**REVISION HISTORY**

Revision	Description of Changes	Date
4	Rebranding to <b>onsemi</b> format.	3/23/2026

This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.

**TO-247-3LD**  
**CASE 340CX**  
**ISSUE A**

DATE 06 JUL 2020



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 - 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.58	4.70	4.82
A1	2.20	2.40	2.60
A2	1.40	1.50	1.60
D	20.32	20.57	20.82
E	15.37	15.62	15.87
E2	4.96	5.08	5.20
e	~	5.56	~
L	19.75	20.00	20.25
L1	3.69	3.81	3.93
ØP	3.51	3.58	3.65
Q	5.34	5.46	5.58
S	5.34	5.46	5.58
b	1.17	1.26	1.35
b2	1.53	1.65	1.77
b4	2.42	2.54	2.66
c	0.51	0.61	0.71
D1	13.08	~	~
D2	0.51	0.93	1.35
E1	12.81	~	~
ØP1	6.60	6.80	7.00

**GENERIC MARKING DIAGRAM\***



- XXXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>TO-247-3LD</b>	<b>PAGE 1 OF 1</b>

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